

Conductive Classification and Testing

- Migratory Anti-Stats
 Inherently Dissipative Polymers
 Carbon (Powder, Fiber, Nanotubes)

- EMI Shielding
 Thermal Conductivity



Conductivity

- Electrical
- · Measure of a material's ability to carry an electric current
- Thermal
- Measure of a material's ability to conduct/transfer heat

Resistivity

· Measure of how strongly a material opposes the flow of electric current

QUICK REFRESHER ON NOTATION

- How many ways can you write "One Billion Ohms"?
 - 1,000,000,000 Ω
 - 1x10^9 Ω
 - 1.0E+9 Ω
 - 1x10⁹ Ω
 - 1e9 Ω
 - 10⁹ Ω
 - 1 GΩ

CONDUCTIVE CLASSIFICATION

Antistatic

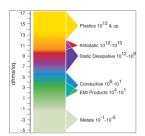
- Cleanliness
- Prevent Dirt & Dust build up

Static Dissipative

- Protect Delicate Electronics
- · Prevent Explosions

Conductive (Current-Carry Devices)

- Electrical Contacts
 - Electrical Contacts
 Electrical Circuits
- Shielding
 - · Provide Protection against RFs



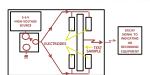
FIRE STATIC DECAY TESTING

Static Decay Rate

- · Measures seconds to decay
- 5000V to 50V
- 12% Relative Humidity

Standards/Specifications

- MIL PRF 81705 D
- NFPA 56A
- · Numerous Others





RTP SURFACE TESTING

Surface Resistivity (ohms/square)

Surface Resistance (ohm)

Standards/Specifications

- ASTM D257
- ESD STM11.11
- IEC 60079-0
- Numerous others

RTP SURFACE RESISTIVITY TEST

- · Small Samples
- · Irregular Part Shapes
- In-Field Test
- Units = ohms/square



Voyager SRM-110



RTP SURFACE RESISTIVITY TEST



Guarded Ring Electrode

Flat Specimen

Precise Measurement

Units = ohms/square

ATP SURFACE RESISTANCE TEST

Surface Resistance Meter

- · Point to Point
- Measuring small & critical areas on part
- Units = ohm





FIR SURFACE RESISTANCE TEST

Another Surface Resistance Meter

- Point to Point, 5lb weighted probes
- Typically used for flooring applications and large parts
- Units = ohm

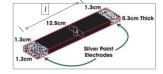




RTP VOLUME RESISTIVITY TEST



- ρ = Volume Resistivity
- R = Resistance
- A = Cross-sectional Area
- l = Length



OVERVIEW

Overview of Conductive Modifiers

- Migratory Anti-Stats
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 Carbon (Powder, Fiber, Nanotubes)

- EMI Shielding
 Thermal Conductivity

ATE CONDUCTIVE MODIFIERS



PERCOLATION CURVE

Conductivity Percolation Curve 1.0E+14 1.0E+13 1.0E+12 1.0E+10 1.0E+10 1.0E+09 1.0E+08 1.0E+06 1.0E+06 1.0E+06 1.0E+04 1.0E+02 1.0E+01 1.0E+02 1.0E+02 1.0E+01 1.0E+02 1.0E+02 1.0E+02 IDP / All-Polymeric Additive Loading (Wt. %)

MIGRATORY ANTI-STATIC AGENTS

- Migrating surfactant based not bonded to resin
- · Temperature & humidity dependent
 - Best at room temperature & high humidity
- Colorable
- · Liquids & semi-solids with low boiling points
- · Compatible only with low temp. resins
 - Olefins, Styrenics, PVC
- · Economical/commodity materials



INHERENTLY DISSIPATIVE POLYMERS (IDP)

All-polymeric, based on IDP

- · Typically consist of PE oxide
- Other block dictates compatibility
- Forms a co-continuous morphology with the base resin

Over 20 different resin systems

Limited process temps (< 520 °F)

Surface resistivity

- Standard: 10¹⁰ to 10¹¹ ohm/sq
- PLUS: 108 to 109 ohm/sq

Static decay rate

- Standard < 2.0 s
- PLUS < 0.5 s



PermaStat®

PERMASTAT® TECHNOLOGY BENEFITS

Permanent ESD protection – not dependent on migration, humidity or temperature

Clean Technology – non sloughing with FDA and Biocompatible grades available

Transparent grades available and fully colorable

Base resin properties retained

PermaStat PLUS® can meet ATEX requirements

PTP TYPICAL APPLICATIONS

Reticle Boxes







FIRE WHAT IS ATEX?

ATMOSPHERE EXPLOSIVE

· Potentially explosive environments

Began as a European Directive

- Standardize compliance procedure
- Now seen in US and other countries (IECEx)

Typic	cal A	TEX 8	X & IECEx Marking							
CE	0359	⟨Ex⟩	П	2	G	Ex	db	IIC	T4	Gb
1	1	1	1	1	1	1	1	1	1	1
Complies with European Directive*	Notified Body Number*	Specific Marking for Explosion Protection*	Equipment Group*	Equipment Category*	Environment*	Explosion Protection	Protection Type	Atmosphere Group	Temperature Class	Equipmen Protection Level (EPL

ATEX TESTING

Actual requirements defined by customer

Tests could include:

- Surface Resistance (almost always included)
 Relative Thermal Index (RTI)
- · Chemical Resistance
- · Impact (Low temperature)
- Ultra Violet (UV)
- High Humidity Aging Testing
 Flame Retardant (FR)

Need to fully identify all requirements for proper material selection

ATEX SURFACE RESISTANCE

Specific test

- · Isolation resistance
- <10⁹ at 50% R.H.
- <10¹¹ at 30% R.H.
- · Tested at 500 V

Different from the standard surface resistance or resistivity widely used in the plastic industry

- IEC 60093
- ASTM D 257
- ESD STM11.11

No real correlation

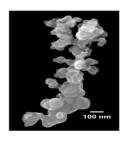


Mining Personal protective equipment Food, chemicals, and paint industries Hand-held equipment Industrial equipment (pneumatic, hydraulic, venting systems, pumps)

CONDUCTIVE CARBON BLACK

Characterized by:

- Structure
- · Size of particles
- Porosity
- · Surface Chemistry



RTP CONDUCTIVE CARBON BLACK

Permanent

Black color only

Sloughing / Marking / Crayoning

Dissipative or conductive

- SR 10³ to 10⁹ ohm/sq VR 10⁰ to 10⁶ ohm-cm



CARBON BLACK **APPLICATIONS**



Electronic device trays PP, PS, PC



Storage bins & totes



Pipette tips



Fuel filler tubes

FTP CARBON / GRAPHITE FIBER

Non-sloughing

Colorable

Anisotropic shrinkage

Reinforcing

Dissipative or conductive

- SR 102 to 106 ohm/sq
- VR 10⁻¹ to 10⁴ ohm-cm



Chopped Fiber %" long "bundles"



Milled Fiber pulverized

FIF CARBON FIBER APPLICATIONS









Card printer chassis

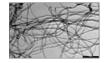
GTE CARBON NANOTUBES (CNT)

> 90% graphite

Hollow

10 nanometer diameter

High L/D ratio





RTP CNT SIZE DIFFERENCE



RTP PRIMARY BENEFITS OF CNTS

Uniform electrical conductivity -

prevent hot spots and protect sensitive electronics

Effective at low loadings -

clean product with low SG and good surface finish

Isotropic Properties -

non reinforcing, behaves like neat resin

Ability to use regrind – maintains conductivity with additional processing

FIFT ELECTRICAL CONDUCTIVITY

SEM (2000x) of typical CNT compound

- · Smooth surface finish
- Uniform shading is a direct result of uniform electrical conductivity

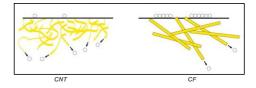
SEM (2000x) of typical CF compound

- Rough surface finish
- White shading indicates a point of high conductivity "Hot spot"
 Possible conductive particle generation





HOT SPOTS



Fewer Hot Spots

Lower Voltage Retention

Reduced Tribocharging

RTP ELECTRONICS INDUSTRY **APPLICATIONS**

- · Hard disc drive (HDD) handling components
- · Silicon wafer handling components
- Semiconductor chip trays
- · ESD shipping trays







ATP OVERVIEW

- Migratory Anti-Stats
 Inherently Dissipative Polymers
 Carbon (Powder, Fiber, Nanotubes)

More Specialized Technology

- EMI Shielding
 Thermal Conductivity

ATP EMI SHIELDING

 $\underline{\mathbf{E}}$ lectro $\underline{\mathbf{M}}$ agnetic $\underline{\mathbf{I}}$ nterference = EMI

Emitted from a source or Received by a device

Frequency range of 1 kHz to 10 GHz

Faraday Cage Principle:

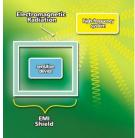
Barrier that reflects or conducts signals to ground

Shielding provides "Immunity"

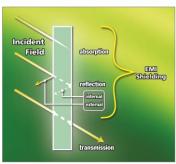


EMI shields protect sensitive devices











Electrically Conductive modifiers:

- Carbon Powder
- · Carbon fiber
- Graphite
- · Stainless steel fiber
- · Nickel-coated carbon fiber
- · Other metallic additives

ADDITIVE COMPARISON



Stainless Steel Fiber

- Non-ReinforcingEquivalent shrinkage to neat resin
- Moderate shielding performance
- Colorable



Nickel-Coated Carbon Fiber Reinforcing High shielding performance Higher cost Less colorable

ATP CUBE BLENDS

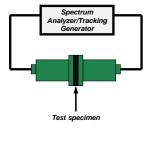


COAXIAL TRANSMISSION ATP LINE TEST

- ASTM D 4935
 Direct Measurement on Flat Specimens
- Fast and Repeatable

- Relative Ranking
 Frequency range of 30 MHz to 1.5
- GHz
 Units = Decibels of SE





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REVIEW OF SHIELDING OPTIONS



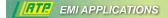
- · VR is key parameter
- SR is misleading
- SE dependent on filler loading and wall thickness
- · Easily Grounded



- · SR key parameter
- Other surfaces insulative
- conductivity & thickness
- · Care in grounding required
- · Can flake or chip off



- · Uniform Conductivity
- SR easily measured
- · Easily grounded







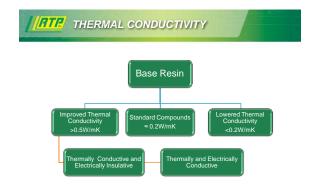
Motor Housing PC/NCCF

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More Specialized Technology

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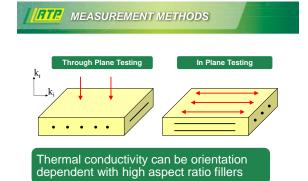


Electrically Conductive

- Carbon fiber
- · Milled carbon fiber
- Pitch fiber
- Graphite
- Anything carbon-based

Electrically Insulative

Ceramics



ADVANTAGES

Why convert metal?

- Injection mold complex geometr
- Increase surface area
- Weight reduction
- · Simplified manufacturing
- · Corrosion resistance
- Improved wear performance
- Cost Reduction
- Increased Design Freedom



Unfilled Plastic Thermally Conductive Plastic Metal Plastic Heat Source Heat source Heat source Heat source Heat source Heat starported through insulative plastic at the same plast

In many cases, thermally conductive plastic can perform as well as metal despite having lower thermal conductivity!

FTE DISADVANTAGES
Processing challenges
Highly filled Freeze off in mold
Physical properties
High specific gravity Brittleness
Limited thermal conductivity Diamond
Stainless Steel (316L) Al ₂ O ₃ (316L)
0.01 1.0 5.0 20 250 400 2300 High
Plastics Elastomers Thermally Conductive Compounds



Technology	Pros	Cons
Migratory Antistats	• Economical	Non-permanent Process temperature limited Humidity dependent
Inherently Dissipative Polymer PermaStat®	Permanent Transparent availability Colorable No loss of mechanical properties	Limited to dissipative range Process temperature limited
Carbon Black	Economical Dissipative or conductive Resists Tribocharging	Sloughing Black only Lower impact strength
Carbon Fiber	Dissipative or conductive Reinforcing Non-sloughing	Anisotropy Poor tribocharging
Carbon Nanotubes	Dissipative or conductive Superior tribocharging performance Minimal effect on mechanical and viscosity Low Liquid Particle Count (LPC)	Cost Black only
Metallic Additives	EMI/RFI shielding Highly conductive	Limited colorability Higher specific gravity
Ceramic Additives	Provide Thermal Conductivity Electrically insulative	*High loadings required *Reduction in physical properties

